CC1350 RF

VDDS Decoupling Capacitors

Place L1 and C8 close to pin 33

VDDR Decoupling Capacitors

R67, R68, R69 select source of power for RF switch; only mount one of them

Place L1 and C8 close to pin 33

Pin 45 Pin 48

VDDR Decoupling Capacitors

Pin 13 Pin 34

CC1350 IO block placed on page 2.

Sub-1 GHz RF section

2.4 GHz RF section

CTL=High selects PORT3
CTL=Low selects PORT2

2.4 GHz RF section

C24 and C59 for antenna matching

L32, C71 and C23 for antenna matching

CC1350 I0 block

placed on page 2.
XDS110 Debugger Interface

P10 selects the voltage source for the level shifters.
When powering CC1350 from the XDS supply, connect jumper between pins 1 and 2.
When powering CC1350 from the external supply, connect jumper between pins 2 and 3.

Jumper M12 to be mounted between pins 1 and 2 on P10

Jumpers M1-M11 to be mounted on header P4

Use P5 for debugging CC1350 with an external debugger (requires that all jumpers on P4 be removed)

Use P7 for debugging external targets (requires that all jumpers on P4 be removed)

XDS-RST = 0 -> output = 0
XDS-RST = 1 -> output = Hi-Z
TMS signal is bidirectional. TMS_DIR used to control direction of level shifter
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